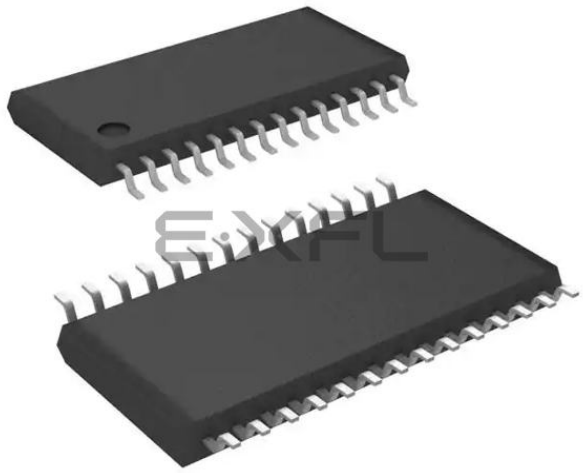
Infineon Technologies - XMC1202T028X0032ABXUMA1 Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, I²S, POR, PWM, WDT
Number of I/O	20
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 14x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-28-16
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xmc1202t028x0032abxuma1

Table of Contents

About this Document

This Data Sheet is addressed to embedded hardware and software developers. It provides the reader with detailed descriptions about the ordering designations, available features, electrical and physical characteristics of the XMC1200 series devices.

The document describes the characteristics of a superset of the XMC1200 series devices. For simplicity, the various device types are referred to by the collective term XMC1200 throughout this document.

XMC™1000 Family User Documentation

The set of user documentation includes:

- **Reference Manual**
  – decribes the functionality of the superset of devices.
- **Data Sheets**
  – list the complete ordering designations, available features and electrical characteristics of derivative devices.
- **Errata Sheets**
  – list deviations from the specifications given in the related Reference Manual or Data Sheets. Errata Sheets are provided for the superset of devices.

Attention: Please consult all parts of the documentation set to attain consolidated knowledge about your device.

Application related guidance is provided by **Users Guides** and **Application Notes**.

Please refer to **http://www.infineon.com/xmc1000** to get access to the latest versions of those documents.

On-Chip Debug Support

- Support for debug features: 4 breakpoints, 2 watchpoints
- Various interfaces: ARM serial wire debug (SWD), single pin debug (SPD)

1.1 Ordering Information

The ordering code for an Infineon microcontroller provides an exact reference to a specific product. The code “XMC1<DDD>-<Z><PPP><T><FFFF>” identifies:

- <DDD> the derivatives function set
- <Z> the package variant
  - T: TSSOP
  - Q: VQFN
- <PPP> package pin count
- <T> the temperature range:
  - F: -40°C to 85°C
  - X: -40°C to 105°C
- <FFFF> the Flash memory size.

For ordering codes for the XMC1200 please contact your sales representative or local distributor.

This document describes several derivatives of the XMC1200 series, some descriptions may not apply to a specific product. Please see **Table 1**.

For simplicity the term **XMC1200** is used for all derivatives throughout this document.

1.2 Device Types

These device types are available and can be ordered through Infineon’s direct and/or distribution channels.

Table 1 Synopsis of XMC1200 Device Types

Derivative	Package	Flash Kbytes	SRAM Kbytes
XMC1201-T028F0016	PG-TSSOP-28-16	16	16
XMC1201-T028F0032	PG-TSSOP-28-16	32	16
XMC1201-T038F0016	PG-TSSOP-38-9	16	16
XMC1201-T038F0032	PG-TSSOP-38-9	32	16
XMC1201-T038F0064	PG-TSSOP-38-9	64	16
XMC1201-T038F0128	PG-TSSOP-38-9	128	16
XMC1201-T038F0200	PG-TSSOP-38-9	200	16
XMC1200-T038F0200	PG-TSSOP-38-9	200	16

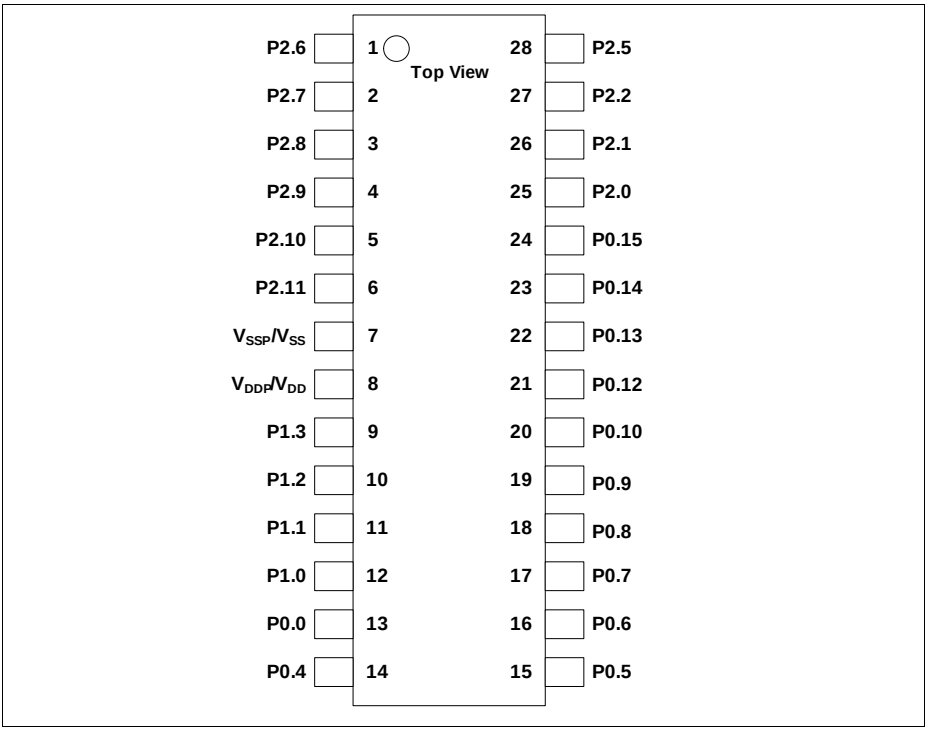

Figure 5 XMC1200 PG-TSSOP-28 Pin Configuration (top view)

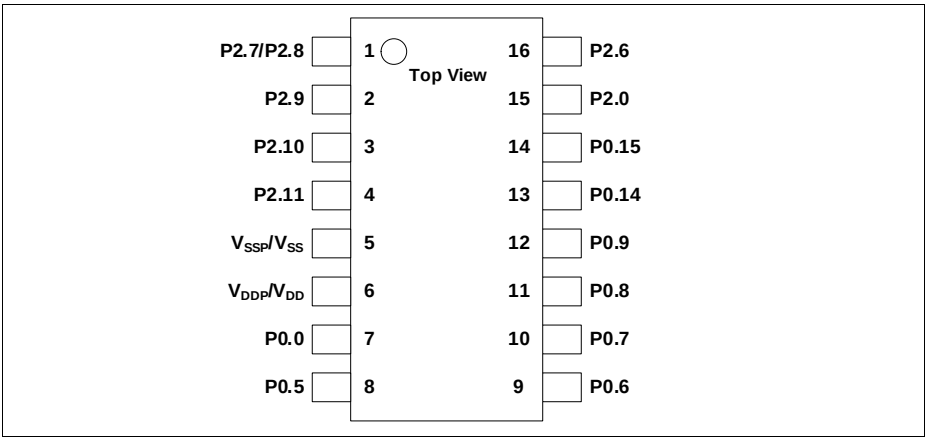

Figure 6 XMC1200 PG-TSSOP-16 Pin Configuration (top view)

2.2.1 Package Pin Summary

The following general building block is used to describe each pin:

Table 5 Package Pin Mapping Description

Function	Package A	Package B	...	Pad Type
Px.y	N	N		Pad Class

The table is sorted by the “Function” column, starting with the regular Port pins (Px.y), followed by the supply pins.

The following columns, titled with the supported package variants, lists the package pin number to which the respective function is mapped in that package.

The “Pad Type” indicates the employed pad type:

- STD_INOUT (standard bi-directional pads)
- STD_INOUT/AN (standard bi-directional pads with analog input)
- High Current (high current bi-directional pads)
- STD_IN/AN (standard input pads with analog input)
- Power (power supply)

Details about the pad properties are defined in the Electrical Parameters.

Table 6 Package Pin Mapping

Function	VQFN 40	TSSOP 38	TSSOP 28	VQFN 24	TSSOP 16	Pad Type	Notes
P0.0	23	17	13	15	7	STD_INOUT	
P0.1	24	18	-	-	-	STD_INOUT	
P0.2	25	19	-	-	-	STD_INOUT	
P0.3	26	20	-	-	-	STD_INOUT	
P0.4	27	21	14	-	-	STD_INOUT	
P0.5	28	22	15	16	8	STD_INOUT	
P0.6	29	23	16	17	9	STD_INOUT	

Table 6 Package Pin Mapping (cont'd)

Function	VQFN 40	TSSOP 38	TSSOP 28	VQFN 24	TSSOP 16	Pad Type	Notes
P2.1	2	36	26	2	-	STD_INOUT/AN	
P2.2	3	37	27	3	-	STD_IN/AN	
P2.3	4	38	-	-	-	STD_IN/AN	
P2.4	5	1	-	-	-	STD_IN/AN	
P2.5	6	2	28	-	-	STD_IN/AN	
P2.6	7	3	1	4	16	STD_IN/AN	
P2.7	8	4	2	5	1	STD_IN/AN	
P2.8	9	5	3	5	1	STD_IN/AN	
P2.9	10	6	4	6	2	STD_IN/AN	
P2.10	11	7	5	7	3	STD_INOUT/AN	
P2.11	12	8	6	8	4	STD_INOUT/AN	
VSS	13	9	7	9	5	Power	Supply GND, ADC reference GND
VDD	14	10	8	10	6	Power	Supply VDD, ADC reference voltage/ ORC reference voltage
VDDP	15	10	8	10	6	Power	When VDD is supplied, VDDP has to be supplied with the same voltage.

3 Electrical Parameter

This section provides the electrical parameter which are implementation-specific for the XMC1200.

3.1 General Parameters

3.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the XMC1200 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the “Symbol” column:

- **CC**
  Such parameters indicate **C**ontroller **C**haracteristics, which are distinctive feature of the XMC1200 and must be regarded for a system design.
- **SR**
  Such parameters indicate **S**ystem **R**equirements, which must be provided by the application system in which the XMC1200 is designed in.

3.1.4 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation and reliability of the XMC1200. All parameters specified in the following tables refer to these operating conditions, unless noted otherwise.

Table 15 Operating Conditions Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Ambient Temperature	T_A SR	-40	–	85	°C	Temp. Range F
		-40	–	105	°C	Temp. Range X
Digital supply voltage[1)]	V_{DDP} SR	1.8	–	5.5	V	
MCLK Frequency	f_{MCLK} CC	–	–	33.2	MHz	CPU clock
PCLK Frequency	f_{PCLK} CC	–	–	66.4	MHz	Peripherals clock
Short circuit current of digital outputs	I_{SC} SR	-5	–	5	mA	
Absolute sum of short circuit currents of the device	ΣI_{SC_D} SR	–	–	25	mA	

1) See also the Supply Monitoring thresholds, **Chapter 3.3.2**.

Table 16 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Input low voltage on port pins (Large Hysteresis)	V_{ILPL}	SR	–	0.08 × V_{DDP}	V	CMOS Mode (5 V, 3.3 V & 2.2 V)[10]
Input high voltage on port pins (Large Hysteresis)	V_{IHPL}	SR	0.85 × V_{DDP}	–	V	CMOS Mode (5 V, 3.3 V & 2.2 V)[10]
Rise time on High Current Pad[1]	t_{HCPR}	CC	–	9	ns	50 pF @ 5 V[2]
			–	12	ns	50 pF @ 3.3 V[3]
			–	25	ns	50 pF @ 1.8 V[4]
Fall time on High Current Pad[1]	t_{HCPF}	CC	–	9	ns	50 pF @ 5 V[2]
			–	12	ns	50 pF @ 3.3 V[3]
			–	25	ns	50 pF @ 1.8 V[4]
Rise time on Standard Pad[1]	t_R	CC	–	12	ns	50 pF @ 5 V[5]
			–	15	ns	50 pF @ 3.3 V[6]
			–	31	ns	50 pF @ 1.8 V[7]
Fall time on Standard Pad[1]	t_F	CC	–	12	ns	50 pF @ 5 V[5]
			–	15	ns	50 pF @ 3.3 V[6]
			–	31	ns	50 pF @ 1.8 V[7]
Input Hysteresis[8]	HYS	CC	0.08 × V_{DDP}	–	V	CMOS Mode (5 V), Standard Hysteresis
			0.03 × V_{DDP}	–	V	CMOS Mode (3.3 V), Standard Hysteresis
			0.02 × V_{DDP}	–	V	CMOS Mode (2.2 V), Standard Hysteresis
			0.5 × V_{DDP}	0.75 × V_{DDP}	V	CMOS Mode(5 V), Large Hysteresis
			0.4 × V_{DDP}	0.75 × V_{DDP}	V	CMOS Mode(3.3 V), Large Hysteresis
			0.2 × V_{DDP}	0.65 × V_{DDP}	V	CMOS Mode(2.2 V), Large Hysteresis

Table 16 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Pin capacitance (digital inputs/outputs)	C_{IO}	CC	–	10	pF	
Pull-up resistor on port pins	R_{PUP}	CC	20	50	kohm	$V_{IN} = V_{SSP}$
Pull-down resistor on port pins	R_{PDP}	CC	20	50	kohm	$V_{IN} = V_{DDP}$
Input leakage current[9)]	I_{OZP}	CC	-1	1	µA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 105$ °C
Voltage on any pin during V_{DDP} power off	V_{PO}	SR	–	0.3	V	[10)]
Maximum current per pin (excluding P1, V_{DDP} and V_{SS})	I_{MP}	SR	-10	11	mA	–
Maximum current per high currrent pins	I_{MP1A}	SR	-10	50	mA	–
Maximum current into V_{DDP} (TSSOP28/16, VQFN24)	I_{MVDD1}	SR	–	130	mA	[10)]
Maximum current into V_{DDP} (TSSOP38, VQFN40)	I_{MVDD2}	SR	–	260	mA	[10)]
Maximum current out of V_{SS} (TSSOP28/16, VQFN24)	I_{MVSS1}	SR	–	130	mA	[10)]
Maximum current out of V_{SS} (TSSOP38, VQFN40)	I_{MVSS2}	SR	–	260	mA	[10)]

1) Rise/Fall time parameters are taken with 10% - 90% of supply.
2) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.150 ns/pF at 5 V supply voltage.
3) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.205 ns/pF at 3.3 V supply voltage.
4) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.445 ns/pF at 1.8 V supply voltage.
5) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.225 ns/pF at 5 V supply voltage.
6) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.288 ns/pF at 3.3 V supply voltage.
7) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.588 ns/pF at 1.8 V supply voltage.

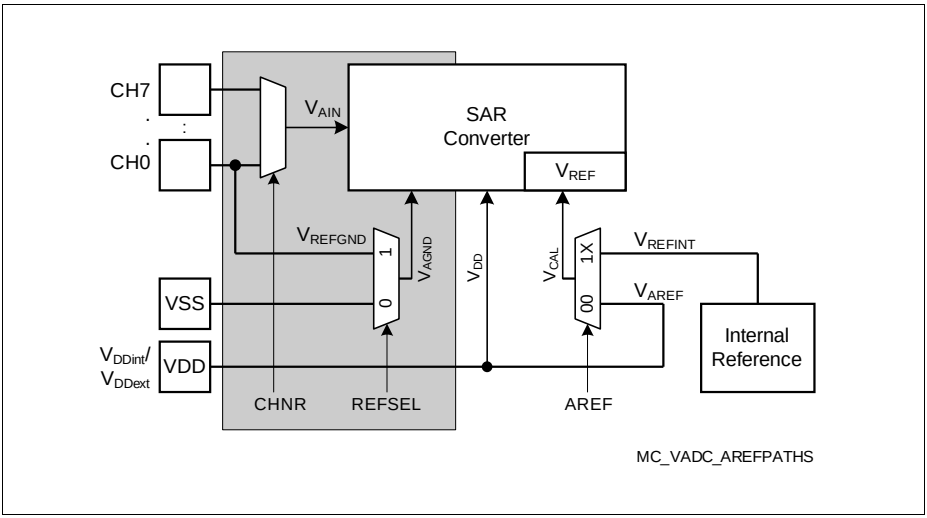

Figure 11 ADC Voltage Supply

Table 21 Power Supply Parameters; V_{DDP} = 5V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.[1]	Max.		
Sleep mode current Peripherals clock disabled Flash active f_{MCLK} / f_{PCLK} in MHz[5]	I_{DDPSD} CC	–	1.8	–	mA	32 / 64
			1.7	–	mA	24 / 48
			1.6	–	mA	16 / 32
			1.5	–	mA	8 / 16
			1.4	–	mA	1 / 1
Sleep mode current Peripherals clock disabled Flash powered down f_{MCLK} / f_{PCLK} in MHz[6]	I_{DDPSR} CC	–	1.2	–	mA	32 / 64
			1.1	–	mA	24 / 48
			1.0	–	mA	16 / 32
			0.8	–	mA	8 / 16
			0.7	–	mA	1 / 1
Deep Sleep mode current[7]	I_{DDPDS} CC	–	0.24	–	mA	
Wake-up time from Sleep to Active mode[8]	t_{SSA} CC	–	6	–	cycles	
Wake-up time from Deep Sleep to Active mode[9]	t_{DSA} CC	–	280	–	µsec	

1) The typical values are measured at T_A = + 25 °C and V_{DDP} = 5 V.
2) CPU and all peripherals clock enabled, Flash is in active mode.
3) CPU enabled, all peripherals clock disabled, Flash is in active mode.
4) CPU in sleep, all peripherals clock enabled and Flash is in active mode.
5) CPU in sleep, Flash is in active mode.
6) CPU in sleep, Flash is powered down and code executed from RAM after wake-up.
7) CPU in sleep, peripherals clock disabled, Flash is powered down and code executed from RAM after wake-up.
8) CPU in sleep, Flash is in active mode during sleep mode.
9) CPU in sleep, Flash is in powered down mode during deep sleep mode.

Table 24 Power-Up and Supply Monitoring Parameters (Operating Conditions apply)[1)] (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
V_{DDP} brownout reset voltage	V_{DDPBO} CC	1.55	1.62	1.75	V	calibrated, before user code starts running
V_{DDP} voltage to ensure defined pad states	V_{DDPPA} CC	–	1.0	–	V	
Start-up time from power-on reset	t_{SSW} SR	–	320	–	µs	Time to the first user code instruction in all start-up modes[4)]
BMI program time	t_{BMI} SR	–	8.25	–	ms	Time taken from a user-triggered system reset after BMI installation is is requested

1) Not all parameters are 100% tested, but are verified by design/characterisation.

2) A capacitor of at least 100 nF has to be added between V_{DDP} and V_{SSP} to fulfill the requirement as stated for this parameter.

3) Valid for a 100 nF buffer capacitor connected to supply pin where current from capacitor is forwarded only to the chip. A larger capacitor value has to be chosen if the power source sink a current.

4) This values does not include the ramp-up time. During startup firmware execution, MCLK is running at 32 MHz and the clocks to peripheral as specified in register CGATSTAT0 are gated.

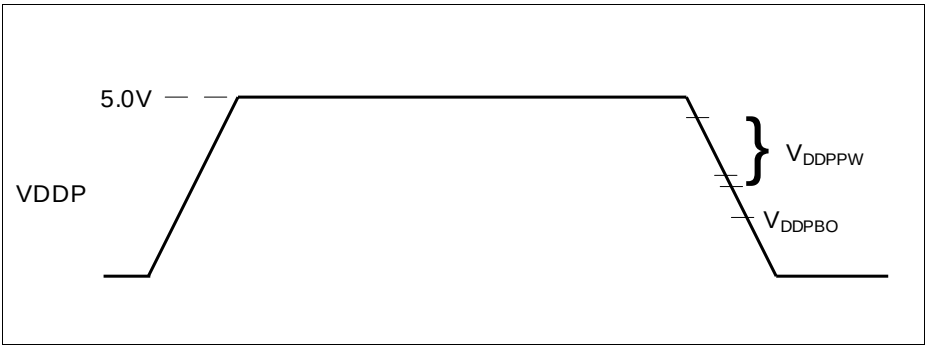

Figure 19 Supply Threshold Parameters

3.3.6 Peripheral Timings

Note: These parameters are not subject to production test, but verified by design and/or characterization.

3.3.6.1 Synchronous Serial Interface (USIC SSC) Timing

The following parameters are applicable for a USIC channel operated in SSC mode.

Note: Operating Conditions apply.

Table 29 USIC SSC Master Mode Timing

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
SCLKOUT master clock period	t_{CLK}	CC	62.5	–	–	ns	
Slave select output SELO active to first SCLKOUT transmit edge	t_1	CC	80	–	–	ns	
Slave select output SELO inactive after last SCLKOUT receive edge	t_2	CC	0	–	–	ns	
Data output DOUT[3:0] valid time	t_3	CC	-10	–	10	ns	
Receive data input DX0/DX[5:3] setup time to SCLKOUT receive edge	t_4	SR	80	–	–	ns	
Data input DX0/DX[5:3] hold time from SCLKOUT receive edge	t_5	SR	0	–	–	ns	

Table 30 USIC SSC Slave Mode Timing

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
DX1 slave clock period	t_{CLK}	SR	125	–	–	ns	
Select input DX2 setup to first clock input DX1 transmit edge[1]	t_{10}	SR	10	–	–	ns	
Select input DX2 hold after last clock input DX1 receive edge[1]	t_{11}	SR	10	–	–	ns	
Receive data input DX0/DX[5:3] setup time to shift clock receive edge[1]	t_{12}	SR	10	–	–	ns	
Data input DX0/DX[5:3] hold time from clock input DX1 receive edge[1]	t_{13}	SR	10	–	–	ns	
Data output DOUT[3:0] valid time	t_{14}	CC	-	–	80	ns	

1) These input timings are valid for asynchronous input signal handling of slave select input, shift clock input, and receive data input (bits DXnCR.DSEN = 0).

3.3.6.2 Inter-IC (IIC) Interface Timing

The following parameters are applicable for a USIC channel operated in IIC mode.

Note: Operating Conditions apply.

Table 31 USIC IIC Standard Mode Timing[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Fall time of both SDA and SCL	t_1 CC/SR	-	-	300	ns	
Rise time of both SDA and SCL	t_2 CC/SR	-	-	1000	ns	
Data hold time	t_3 CC/SR	0	-	-	µs	
Data set-up time	t_4 CC/SR	250	-	-	ns	
LOW period of SCL clock	t_5 CC/SR	4.7	-	-	µs	
HIGH period of SCL clock	t_6 CC/SR	4.0	-	-	µs	
Hold time for (repeated) START condition	t_7 CC/SR	4.0	-	-	µs	
Set-up time for repeated START condition	t_8 CC/SR	4.7	-	-	µs	
Set-up time for STOP condition	t_9 CC/SR	4.0	-	-	µs	
Bus free time between a STOP and START condition	t_{10} CC/SR	4.7	-	-	µs	
Capacitive load for each bus line	C_b SR	-	-	400	pF	

1) Due to the wired-AND configuration of an IIC bus system, the port drivers of the SCL and SDA signal lines need to operate in open-drain mode. The high level on these lines must be held by an external pull-up device, approximalely 10 kOhm for operation at 100 kbit/s, approximately 2 kOhm for operation at 400 kbit/s.

Table 32 USIC IIC Fast Mode Timing[1)]

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Fall time of both SDA and SCL	t_1 CC/SR	20 + 0.1*C_b [2)]	-	300	ns	
Rise time of both SDA and SCL	t_2 CC/SR	20 + 0.1*C_b	-	300	ns	
Data hold time	t_3 CC/SR	0	-	-	µs	
Data set-up time	t_4 CC/SR	100	-	-	ns	
LOW period of SCL clock	t_5 CC/SR	1.3	-	-	µs	
HIGH period of SCL clock	t_6 CC/SR	0.6	-	-	µs	
Hold time for (repeated) START condition	t_7 CC/SR	0.6	-	-	µs	
Set-up time for repeated START condition	t_8 CC/SR	0.6	-	-	µs	
Set-up time for STOP condition	t_9 CC/SR	0.6	-	-	µs	
Bus free time between a STOP and START condition	t_{10} CC/SR	1.3	-	-	µs	
Capacitive load for each bus line	C_b SR	-	-	400	pF	

1) Due to the wired-AND configuration of an IIC bus system, the port drivers of the SCL and SDA signal lines need to operate in open-drain mode. The high level on these lines must be held by an external pull-up device, approximalely 10 kOhm for operation at 100 kbit/s, approximately 2 kOhm for operation at 400 kbit/s.

2) C_b refers to the total capacitance of one bus line in pF.

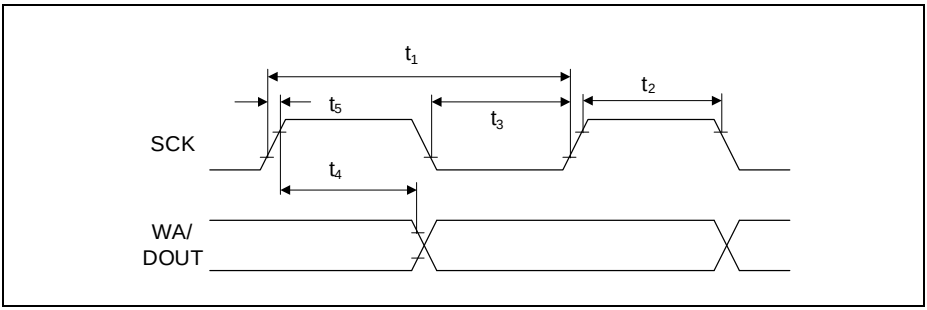

Figure 24 USIC IIS Master Transmitter Timing

Table 34 USIC IIS Slave Receiver Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clock period	t_6 SR	$4/f_{MCLK}$	-	-	ns	
Clock HIGH	t_7 SR	0.35 x t_{6min}	-	-	ns	
Clock Low	t_8 SR	0.35 x t_{6min}	-	-	ns	
Set-up time	t_9 SR	0.2 x t_{6min}	-	-	ns	
Hold time	t_{10} SR	10	-	-	ns	

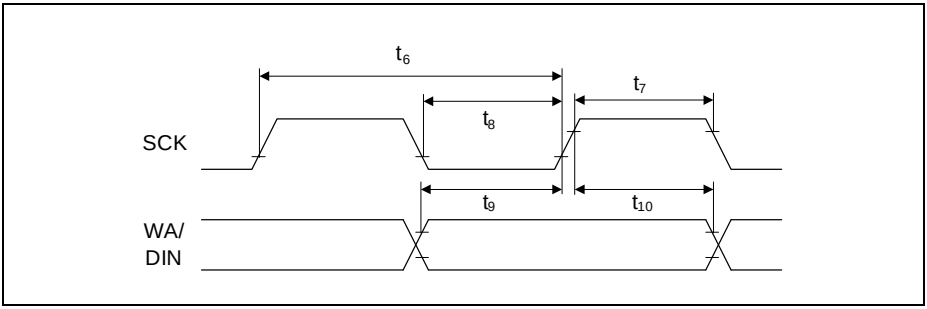

Figure 25 USIC IIS Slave Receiver Timing

4 Package and Reliability

The XMC1200 is a member of the XMC™1000 Family of microcontrollers. It is also compatible to a certain extent with members of similar families or subfamilies.

Each package is optimized for the device it houses. Therefore, there may be slight differences between packages of the same pin-count but for different device types. In particular, the size of the exposed die pad may vary.

If different device types are considered or planned for an application, it must be ensured that the board layout fits all packages under consideration.

4.1 Package Parameters

Table 35 provides the thermal characteristics of the packages used in XMC1200.

Table 35 Thermal Characteristics of the Packages

Parameter	Symbol	Limit Values		Unit	Package Types
		Min.	Max.		
Exposed Die Pad Dimensions	Ex × Ey CC	-	2.7 × 2.7	mm	PG-VQFN-24-19
		-	3.7 × 3.7	mm	PG-VQFN-40-13
Thermal resistance Junction-Ambient	$R_{\Theta JA}$ CC	-	104.6	K/W	PG-TSSOP-16-8[1)]
		-	83.2	K/W	PG-TSSOP-28-16[1)]
		-	70.3	K/W	PG-TSSOP-38-9[1)]
		-	46.0	K/W	PG-VQFN-24-19[1)]
		-	38.4	K/W	PG-VQFN-40-13[1)]

1) Device mounted on a 4-layer JEDEC board (JESD 51-5); exposed pad soldered.

Note: For electrical reasons, it is required to connect the exposed pad to the board ground V_{SSP}, independent of EMC and thermal requirements.

4.1.1 Thermal Considerations

When operating the XMC1200 in a system, the total heat generated in the chip must be dissipated to the ambient environment to prevent overheating and the resulting thermal damage.

The maximum heat that can be dissipated depends on the package and its integration into the target board. The “Thermal resistance $R_{\Theta JA}$” quantifies these parameters. The power dissipation must be limited so that the average junction temperature does not exceed 115 °C.

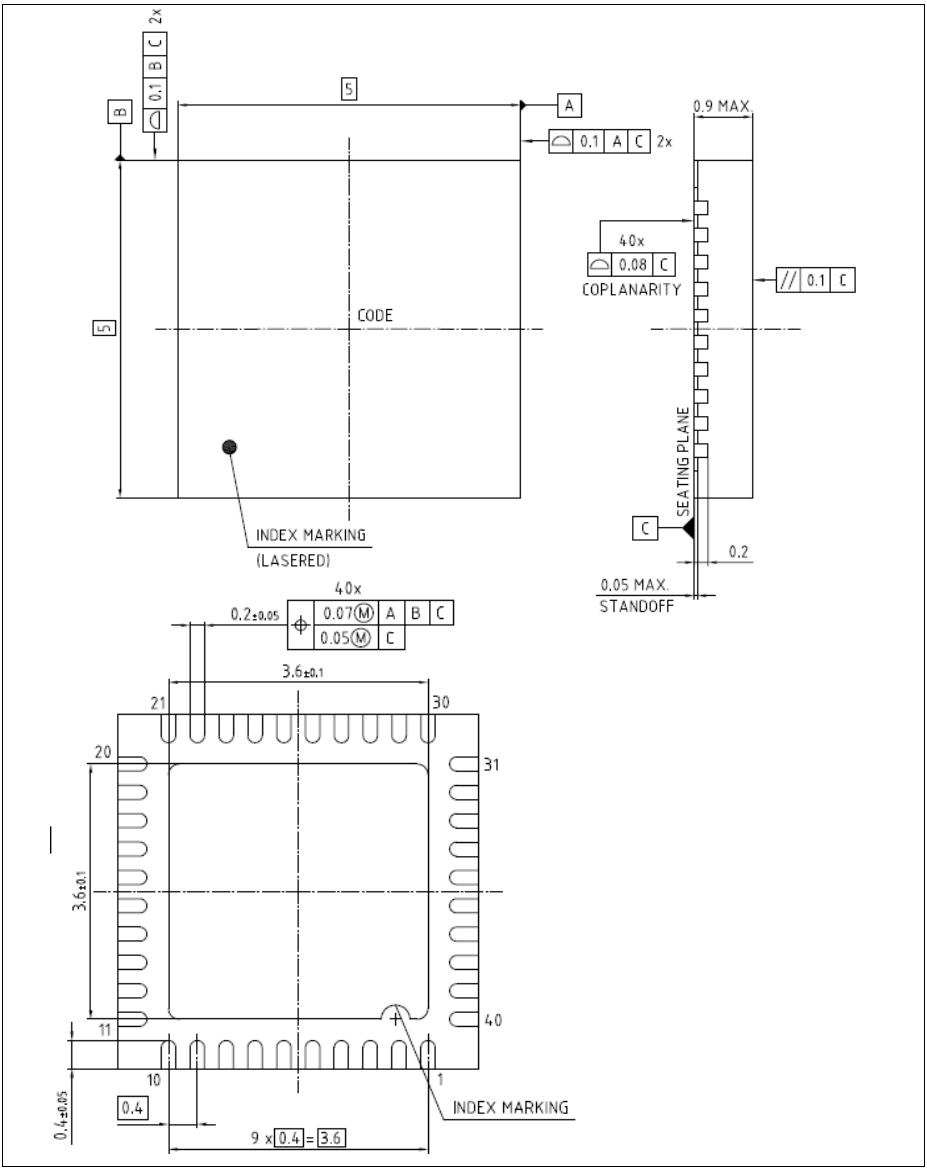

Figure 30 PG-VQFN-40-13

All dimensions in mm.